1. Description
The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.20 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

2. Features
- Low cost
- Simplifies prototyping of SMT IC’s
- Four high voltage high current output GPOs
- Current up to 1 A per HV GPO
- Current sensing resistors
  Variable current sensing configurations
- Optional $V_{DD}$ LED indicator
- Decoupling capacitor included
- Screw terminals for high voltage high current lines
- Optional $I^2C$ pull-up resistors

Note 1  All sizes in millimeters (mm).
3. Top View

Top View Diagram:
- Pins labeled with their connections:
  - PIN1 (VDD)
  - PIN3 (GPI)
  - PIN2 (GPIO0)
  - PIN15 (GPIO2/SCL)
  - PIN16 (GPIO3/SDA)
  - PIN19 (GPIO5)
  - PIN17 (GPIO4)
  - PIN14 (GPIO1)
  - PIN20 (GPIO6)
- Additional components:
  - LED current limit resistor (optional)
  - VDD LED indicator (optional)
- Chip package type and number:
  - SENSE_B to GND (R5 BYPASS)
  - VDD2_A to VDD2_B (solder jumper)
  - HV_GND

4. Bottom View

Bottom View Diagram:
- Pins labeled with their connections:
  - PIN1 (VDD)
  - PIN3 (GPI)
  - PIN2 (GPIO0)
  - PIN15 (GPIO2/SCL)
  - PIN16 (GPIO3/SDA)
  - PIN19 (GPIO5)
  - PIN17 (GPIO4)
  - PIN14 (GPIO1)
  - PIN20 (GPIO6)
- Additional components:
  - LED current limit resistor (optional)
  - VDD LED indicator (optional)
- Chip package type and number:
  - SENSE_B to GND (R5 BYPASS)
  - VDD2_A to VDD2_B (solder jumper)
  - HV_GND

5. Board Schematic

Board Schematic Diagram:
- Various components and connections labeled with their functions.
- Different sections of the circuit are clearly marked with labels and connections.
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